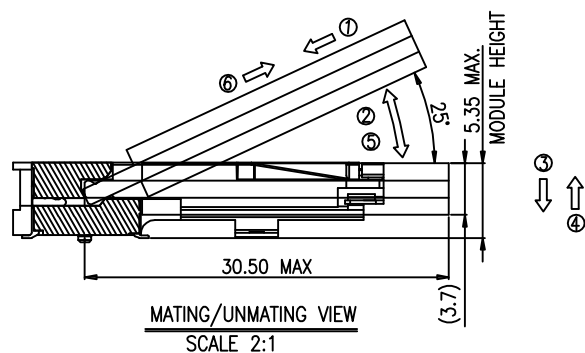
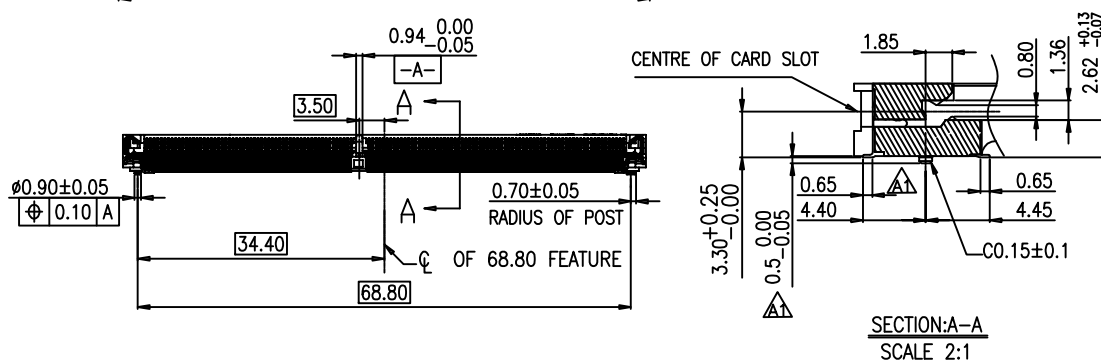
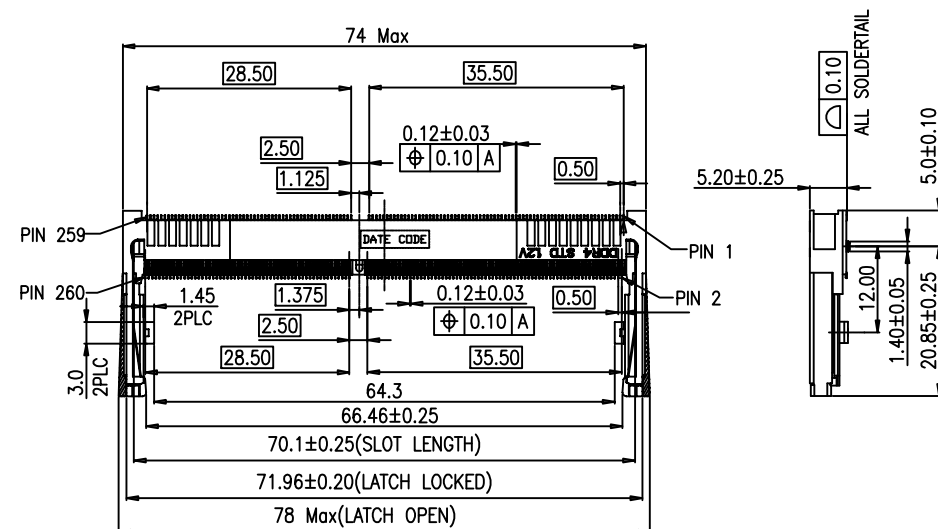


更改 REV	版本号 MODIFICATION
A	EC06685
B	EC06954



MATING: ① INSERTING(25°) → ② ROTATING → ③ FIXED
UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

NOTES:

1.MATERIAL:

- 1.1 HOUSING:LCP,UL94V-0,COLOR:BLACK.
- 1.2 CONTACT:PHOSPHOR BRONZE.
- 1.3 SOLDER PEG AND LATCH:STAINLESS STEEL.

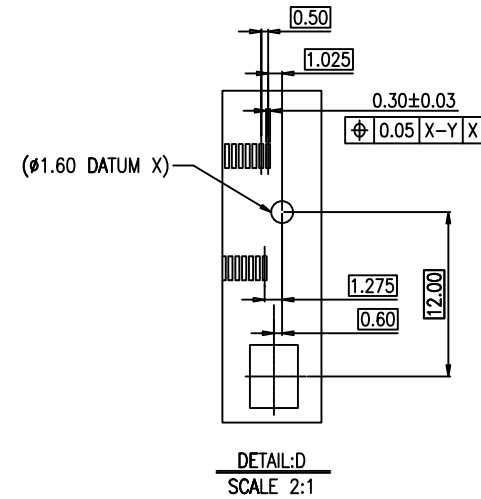
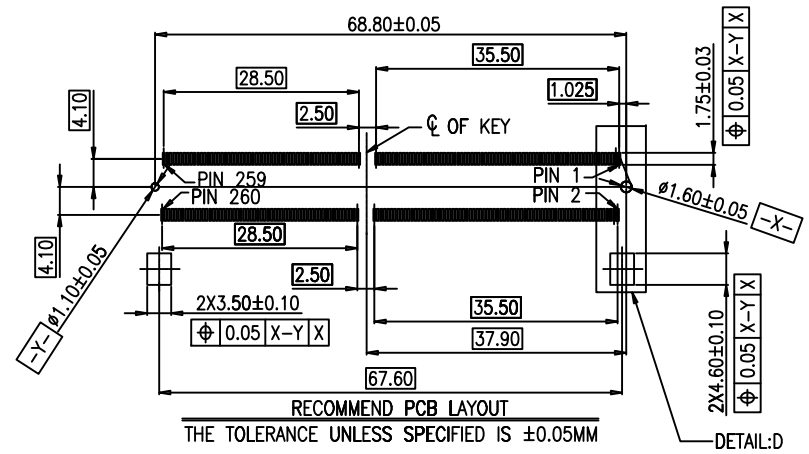
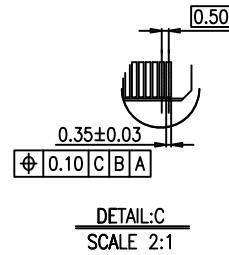
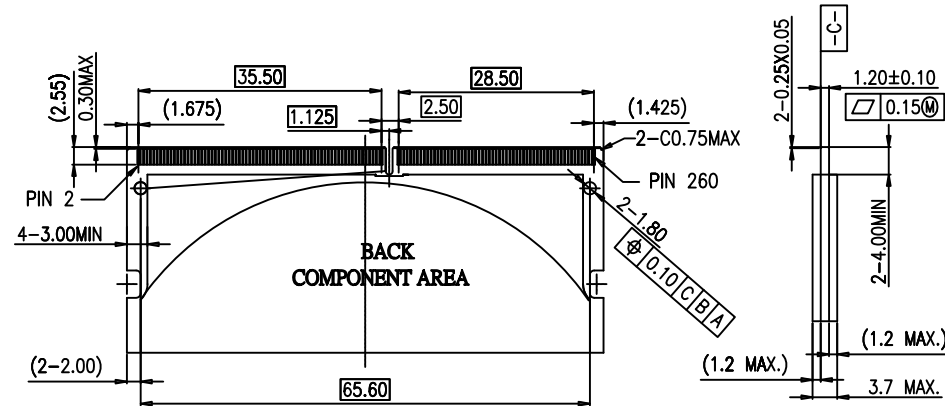
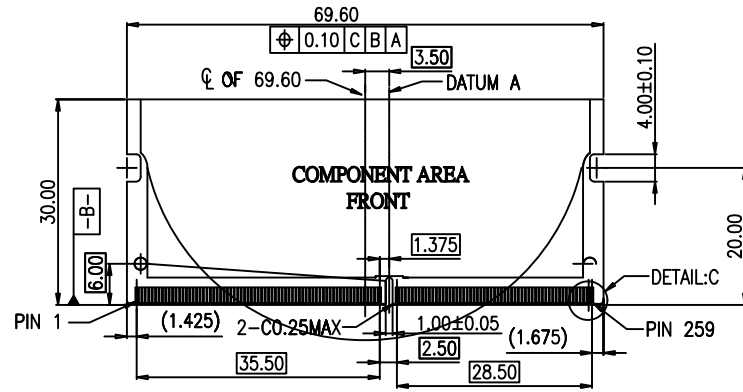
2. FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.
GOLD FALSH PLATING ON SOLDERTAIL.
GOLD PLATING (THICKNESS SEE TABLE) ON CONTACT AREA.
- 2.2 SOLDER PEG:
50u" MIN NICKEL UNDERPLATED ALL OVER.
AU 2u" MAX ON SOLDERTAIL.

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 称(TITLE) DDR4 SO DIMM 260PIN 正向 H:5.2mm	
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
单 位(UNIT) mm	料 号(PART NO.) 7DDR4-F0-0007	图 号(DWG NO.) 7DDR4-F0-0007	
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	SCALE 1:1 PROJ. 更改 REV B



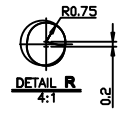
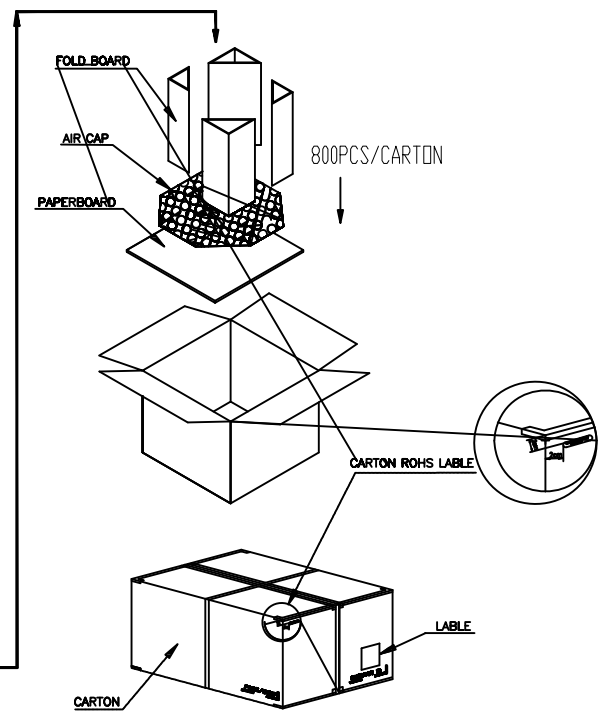
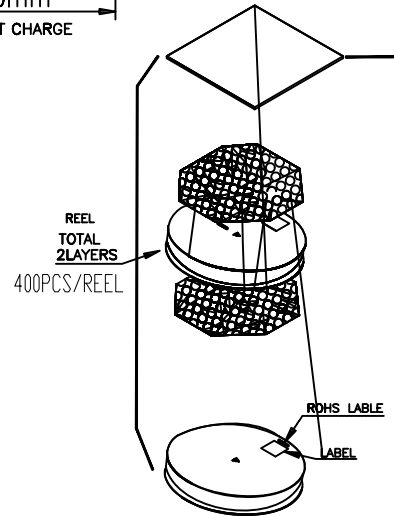
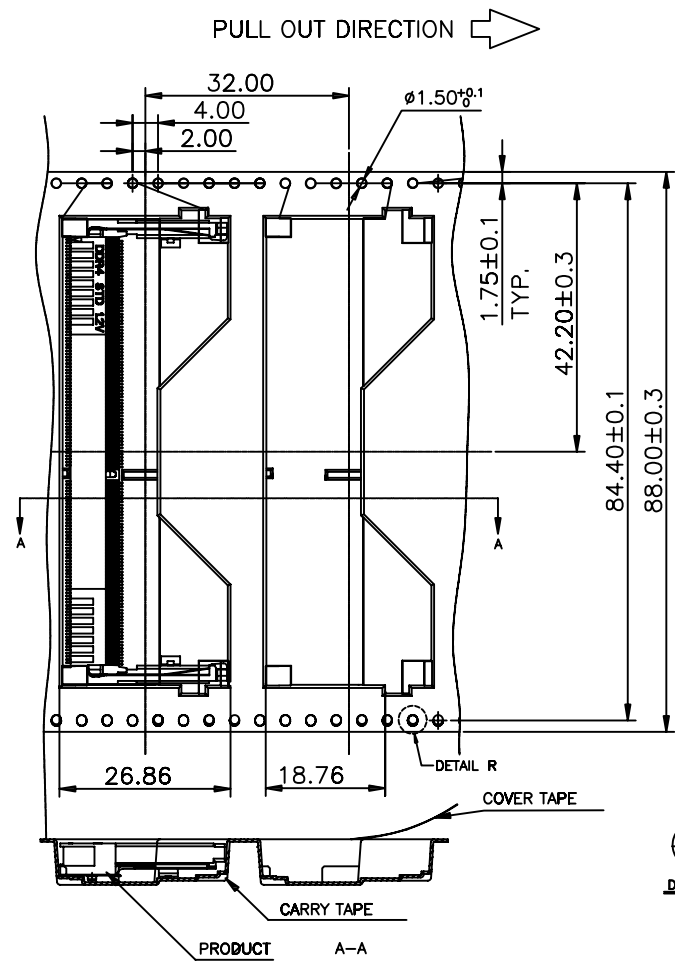
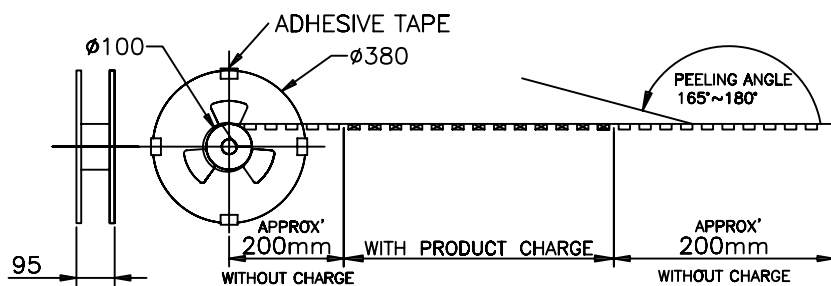
更改 REV	修改内容 MODIFICATION
A	EC06685
B	EC06954



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 称(TITLE)	DDR4 SO DIMM 260PIN 正向 H:5.2mm
X± 0.30	X*± 2 °		
XX± 0.20	XX*± 1 °		
单 位(UNIT)	料 号(PART NO.)	图 号(DWG NO.)	
mm	7DDR4-F0-0007	7DDR4-F0-0007	
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	注 意(SHEET)
			2/3
		比例(SCALE)	1:1
		图 例(LEGEND)	
		更 改(REV)	B



更改 REV	版本号 MODIFICATION
A	EC06685
B	EC06954



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 称(TITLE)	DDR4 SO DIMM 260PIN 正向 H:5.2mm
.X± 0.30	.X*± 2 °		
.XX± 0.20	.XX*± 1 °		
单 位(UNIT)	料 号(PART NO.)	图 号(DWG NO.)	
mm	7DDR4-F0-0007	7DDR4-F0-0007	
审 核(APPROVAL)	核 对(CHECKED)	製 图(DRAWN)	世 界 SCALE 1:1 图 数 SHEET 3/3 更 改 REV B